

Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

([Ceramic Printed circuit board supplier](#))

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

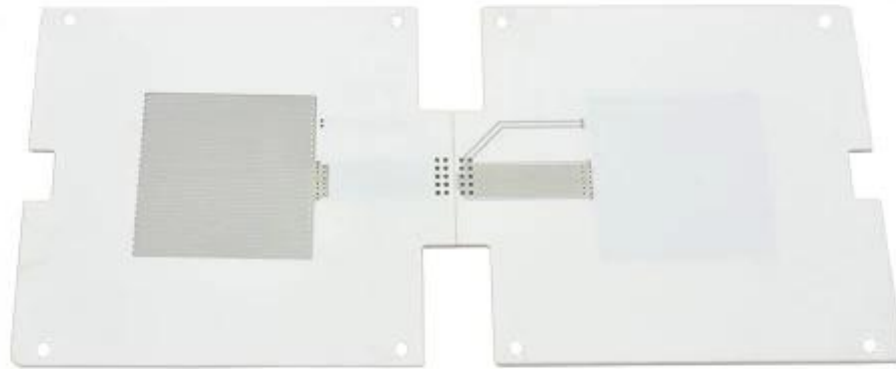
Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK HERE FOR MORE INFORMATION: [DCB Ceramic PCB manufacturers](#)

Product Description

PCB P/N	Q508756-C
Layer Count	2L
Material	Base Ceramics
Board thk	0.55mm
copper thk	1/1oz
Smalleat hole size	1.6mm
No. of holes (pcs)	4
line w/s	1.27mm
Impedance control. Y / N (Tol %)	N
Surface Finishing	ENIG
Solder Mask Silkscreen	N/A
Single board size	Dim X (mm):50;Dim Y (mm):55
Panelisation	Dim X (mm):50;Dim Y (mm):55;No Of UPS:1
Special:peelable mask	N
Routing/Punching	CNC

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www.o-leading.com

[DCB Ceramic PCB suppliers china](#)

Our Team





Certifications



CICC INSPECTION CERTIFICATION



QUALITY MANAGEMENT SYSTEM CERTIFICATE

Certificate No.: 16118Q10347R05

We hereby certify that

O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED

Credit No.: 61691591-000-07-17-2

Registration Add: ROOM 603D 6/F HANG PONT COMMERCIAL BUILDING, 31 TONKIN ST. CHEUNG SHA WAN, KL, HK

Business Add: 1313 Floor 13 Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System** Which fulfills the requirements of the following standards
GB/T19001-2016 idt ISO9001:2015

Scope of certification
Sales of printed circuit boards

Initial Issuance period: February 27, 2018
This certificate is valid during: February 27, 2018 -- February 26, 2021
This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark
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The certification registration scope doesn't include the product/service scope which fail to be covered by the relevant effective administrative permission and qualification permission required by the state. The effectiveness of this certificate shall be evaluated by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit conclusion. The related information of this certification can be searched at the public website of company www.cicc.com.cn.






201726 201VZL430354 - Wiring, Printed - Component

UL ONLINE CERTIFICATIONS DIRECTORY

ZPMV2.E490354
Wiring, Printed - Component

For enhanced search functionality, please visit [UL's e-Product Databases](#).
Click on a product designation for complete information.
[Page Bottom](#)

Wiring, Printed - Component

[See General Information for Wiring, Printed - Components](#) E490354

O-LEADING SUPPLY CHAIN CO LIMITED
Fortune Building, Nanheng West Road
Room 1313
Huizhou, Guangdong 516211, CHINA

Type	Cond Width			SS/ DS/ Diam	Area	Solder		Diper		Flame	RoHS	C
	Min	Edge	Thk			Limits	Temp	Class	DSR			
Hull/Bayer (mass laminate) printed wiring boards.												
O-LEADING-401												
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	130	V-0	-	-	-
O-LEADING-407												
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.2 (0.4)	260	10	170	V-0	NI	-	-
Hull/Bayer printed wiring boards.												
O-LEADING-408												
	0.125 (0.005)	0.125 (0.005)	12 (0.47) 31(1.25)	D6	50.8 (2.0)	260	20	130	V-0	NI	-	-
Single layer printed wiring boards.												
O-LEADING-002												
	0.76 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	105	V-0	NI	-	-
O-LEADING-003												
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	130	V-0	▲	-	-
O-LEADING-033												
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	S5	25.4 (1.0)	260	10	120	V-0	NI	-	-
O-LEADING-205												
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.6 (2.7)	260	10	130	V-0	NI	-	-
O-LEADING-206												
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.6 (2.7)	260	10	130	V-0	NI	-	-

* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.
Last updated on 2017-01-27

Questions? Print this page Terms of Use Page Top

[http://www.ul.com/ulcertportal/en/SECURITY/IRMS/Accessories/Item/ZPMV2.E490354/Component/Wiring,Printed-Component/17](#)



Test Report No. CANEC1805164701 Date: 03 Apr 2018 Page 2 of 8

Test Results:

Test Part Description:

Specimen No. SGS Sample ID Description
SN1 CAN18-051647.001 Green "PCB"

Remarks:

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Mono-bromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Mono-bromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



SGS shall not be held responsible for any errors or omissions in this report. The client is responsible for the accuracy of the data provided. This report is for the client's use only. It is not to be distributed to other parties without the client's written consent. The client is responsible for the accuracy of the data provided. This report is for the client's use only. It is not to be distributed to other parties without the client's written consent.

Member of the SGS Group (SGS SA)

Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching → Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.